

tentative

Туре	Ag [*] Aİ	V _{DRM} / V _{RRM}	V _{DSM} / V _{RSM} [V]	/_{Т(AV)} [А]	Chip Size [mm] x [mm]	Package Options	•
CWP 93-	18 🗹 🗸	1800	1900	165	15.20 12.0	sawn on foil wunsawn wafer win waffle pack	
	*Frontside options					*Please contact IXYS chip sales	

Mechanical Parameters

Area active Area total Wafer size Ø Thickness Material Max. possible chips per wafer Passivation front side Metallization top side top side Recom. wire bonds (AI) Cathode * = Stitchbonds Number / Ø [µm] *8 / 500 Metallization backside solderable (only): Ti / Ni / Ag * Reject Ink Dot Size Recom. Storage Environment sawn on foil unsawn wafer in waffle pack T_{stq}

Ø 0.4-1.0 mm

in org. container, in dry nitrogen < 6 month in org. container, in dry nitrogen < 2 year <2 year in org. container, in dry nitrogen -40... 40 °C

Features

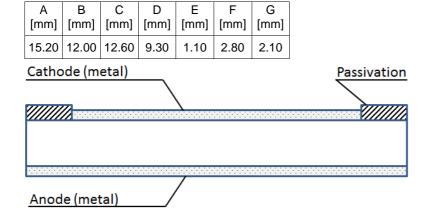
- planar design (non-mesa)
- ultra rugged for easy assembly (flat backside)
- excellent long term stability
- very low leakage current
- very low forward voltage drop

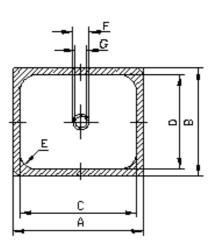
Applications

- DC motor control
- AC power control
- Softstrart AC motor controller
- Light, heat and temperature control
- Solid state relays
- Controlled rectifier circuits

*Sinterable top/bottom side on request

Dimensions





^{1.10} cm² 1.82 cm² 150 mm 380 μm Si 72 Glassivation solderable: Ti / Ni / Ag * bondable: ΑI Gate 1 / 500

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	Ratings				
Symbol	Conditions	min.	typ.	max.	
I _R	$V_D = Vr = Vrr$	$T_{VJ} = 25^{\circ}C$		0.05	mA
		$T_{VJ} = 150^{\circ}C$		20	mΑ
V ₇	$I_{T} = 300 \text{ A}$	$T_{VJ} = 25 ^{\circ}\text{C}$	1	1.40	V
		T _{VJ} = 150 °C		1.35	V
$V_{\tau o}$	For power-loss	s calculations only		0.89	٧
r ,	T _{v.j} = 150 °C		Y	1.50	mΩ
V _{G7}	$V_D = 6 V$	$T_{VJ} = 25$ °C		1.4	\
		$T_{VJ} = -40$ °C		1.5	٧
I _{GT}	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$ 40		145	mΑ
		$T_{VJ} = -40$ °C		tbd	mΑ
V_{GD}	$T_{VJ} = 150 ^{\circ}\text{C}$	$V = \frac{2}{3} V_{DRM}$		0.2	V
I _{GD}				10	m/
I <u>L</u>	t _p =10 μs	$T_{VJ} = 25$ °C $I_G = 0.45 \text{ A} \text{ di}_G/\text{dt} = 0.45 \text{ A}/\mu\text{s}$		450	m/
I _H	R _{GK} = ∞	$T_{V,I} = 25^{\circ}C$ $V_{D} = 6 \text{ V}$		200	m/
t _{gd}	$V_D = \frac{1}{2} V_{DRM}$	$T_{vJ} = 25^{\circ}C$		2	με
	$I_{\rm G} = 0.5 {\rm A}$	$di_{G}/dt = 0.5 A/\mu$			
t _q	V _R = 100 V	$I_{T} = 165 \text{ A}$ -di/dt = 10 A/ μ s			μ
	$t_p = 200 \mu s$	$dv/dt = 20 V/\mu s V_D = \frac{2}{3} V drm T_{V,J} = 125 °C$			
(di/dt) _{cr}	repetitive	$I_{\tau} = 250$ A		150	A/µs
	non repetitive	$I_{T} = 165 \text{ A}$		200	A/µs
	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150 ^{\circ}\text{C}$ $di_{G}/dt = 0.45 ^{\circ}\text{A/}\mu\text{s}$			
	$I_{\rm G} = 0.45 \text{ A}$	$t_p = 200 \ \mu s$ $f = 50 \ Hz$			
(dv/dt) _c ,	$T_{VJ} = 150 ^{\circ}C$	$V_{DR} = \frac{2}{3} V_{DRM}$		1000	V/µs
	R _{GK} = ∞	method 1 (linear voltage rise)			
P _{GM}	$T_{VJ} = 150 ^{\circ}C$	$t_p = 30 \mu s$		10	W
		$t_p = 3E \mu s$		5	W
P_{GAV}				0.5	W
V _{RGM}				10	٧
T _{VJ}		-40		150	°C
I _{T(AV)}	$T_{\rm C} = 100 ^{\circ} \text{C}$	180° rect.		165	А
	$T_{VJ} = {}^{\circ}C$	180° sine		155	A
I _{TSM} *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		2200	Д
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		2400	Α
	T _{VJ} = 150 °C	t = 10 ms (50) Hz, sine		tbd	Α
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		tbd	Α
Pt *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		24200	As
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		23904	A s
	T _{VJ} = 150 °C	t = 10 ms (50) Hz, sine		tbd	A s
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		tbd	
R _{thJC} *	DC current		0.22		K/W

^{*} Data according to assembled product

Data according to IEC 60747

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- to perform joint risk and quality assessments;
- the conclusion of quality agreements;
- to establish joint measures to ensure application specific product capabilities and notify that IXYS may delivery dependent on the realization of any such measures.